

RL78/G23

LED burst dimming control using ELCL

Introduction

This application note describes how to implement the LED burst dimming using the logic and event link controller (ELCL). Burst dimming control is a method that finely control of LED light intensity. It can be applied to control indicators and lighting using LEDs.

Target Device

RL78/G23

When applying the sample program covered in this application note to another microcomputer, modify the program according to the specifications for the target microcomputer and conduct an extensive evaluation of the modified program.

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1. Specifications

In this application note, which is described how to implement a LED burst dimming using ELCL.

Burst dimming control is possible by taking the logical AND two PWM outputs (TO01, TO02) with different duty cycle and PWM output (TO05). Assuming constant current control (switching control) of the DC/DC converter, TO05 is set to a higher frequency (100 kHz or higher) than TO01 and TO02.

And TO01 and TO02 are assumed to be PWM output for controlling the overall light intensity, and set to a frequency (~1 kHz) that does not flicker in the human eye. The combination of these two frequencies provides finely tuned dimming control.

Figure 1-1 shows the system configuration for implement a burst dimming of two LEDs at the same time using ELCL.

Figure 1-1 System Configuration

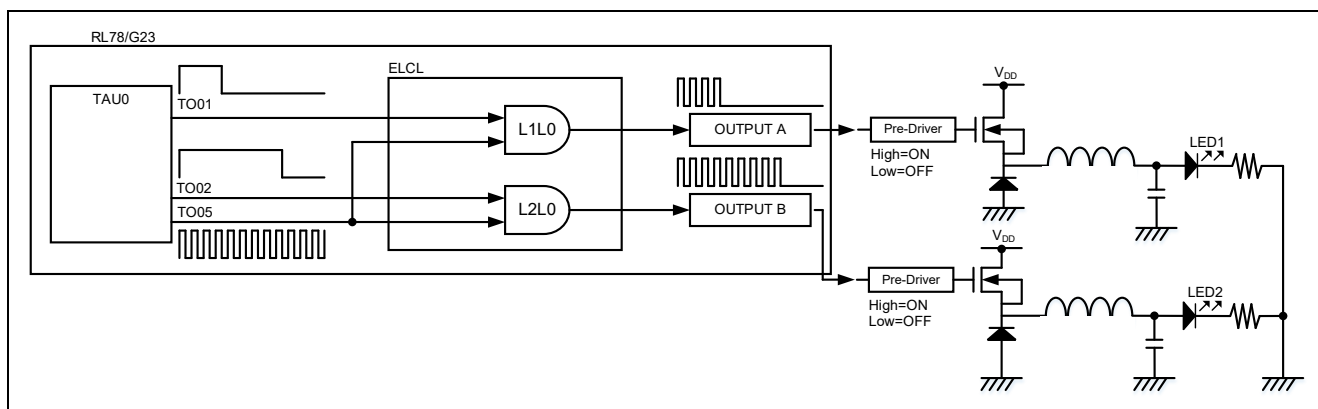
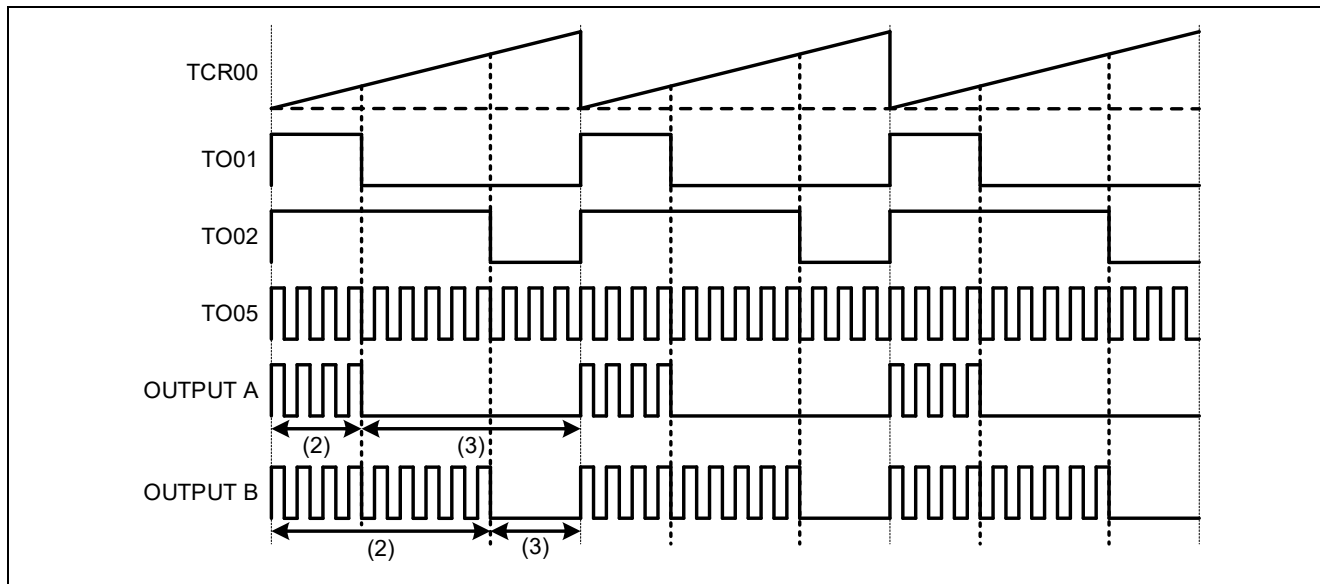


Figure 1-2 shows the timing chart.

- (1) Set TAU01, TAU02 and TAU05 to a PWM output.
- (2) While TO01 is High level, the PWM output from TO05 is enabled and output from OUTPUT A.
In a similar way, while TO02 is High level, the output from OUTPUT B is enabled.
- (3) While TO01 is Low level, the output of OUTPUT A is fixed to Low level. In a similar way, the output of OUTPUT B is fixed to Low level while TO02 is Low level.

Figure 1-2 Timing chart



2. Conditions for Operation Confirmation Test

The sample code with this application note runs properly under the conditions below.

Table 2-1 Operation Confirmation Conditions

Items	Contents
MCU	RL78/G23 (R7F100GLG)
Operating frequencies	High-speed on-chip oscillator clock: 32MHz CPU/peripheral hardware clock: 32MHz
Operating voltage	3.3V LVD0 operations (V_{LVD0}): Reset mode Rising edge TYP. 1.90V Falling edge TYP. 1.86V
Integrated development environment (CS+)	CS+ for CC V8.13.00 from Renesas Electronics Corp.
C compiler (CS+)	CC-RL V1.15 from Renesas Electronics Corp.
Integrated development environment (e ² studio)	e ² studio 2025-04 (25.04.0) from Renesas Electronics Corp.
C compiler (e ² studio)	CC-RL V1.15 from Renesas Electronics Corp.
Integrated development environment (IAR)	IAR Embedded Workbench for Renesas RL78 v5.20.1 from IAR Systems
C compiler (IAR)	
Smart Configurator	V.1.13.0
Board support package (r_bsp)	V.1.90
Emulator	CS+, e ² studio: COM port IAR: E2 Emulator Lite
Board	RL78/G23 Fast Prototyping Board (RTK7RLG230CLG000BJ)

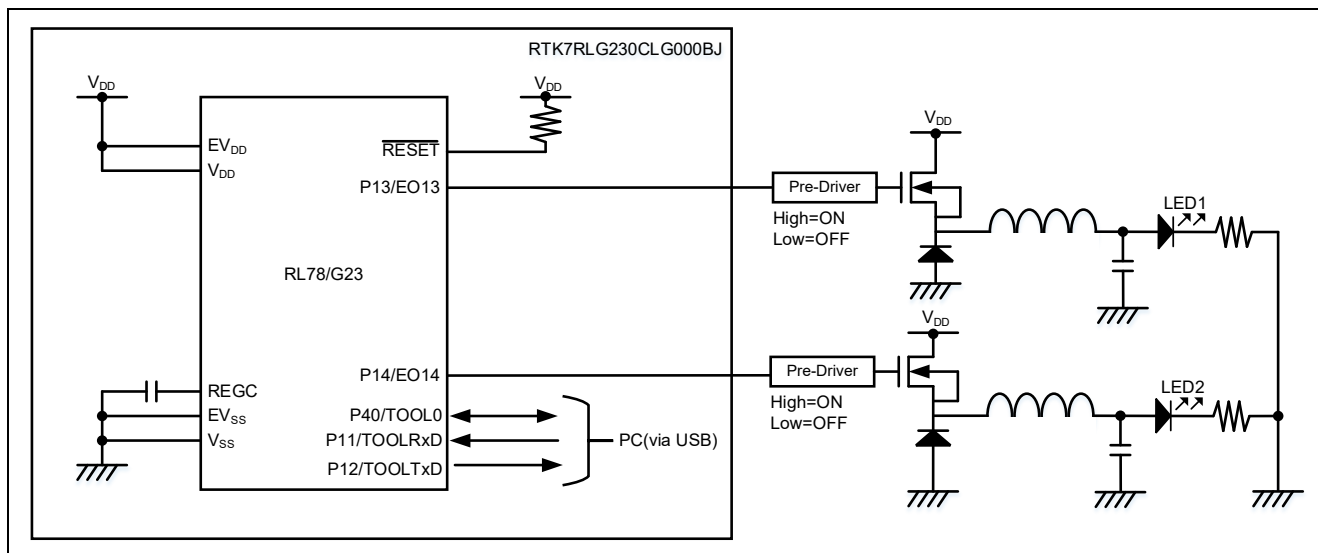
3. Hardware

3.1 Example of Hardware Configuration

Figure 3-1 shows an example of the hardware configuration in this application.

LED1 and LED2 connected to P13 and P14 are configured using LEDs external to the board.

Figure 3-1 Hardware Configuration



Caution 1. This simplified circuit diagram was created to show an overview of connections only.

When actually designing your circuit, make sure the design includes sufficient pin processing and meets electrical characteristic requirements. (Connect each input-only port to V_{DD} or V_{SS} through a resistor.)

Caution 2. Connect the EV_{SS} pin to V_{SS} and the EV_{DD} pin to V_{DD} .

Caution 3. V_{DD} must be held at not lower than the reset release voltage (V_{LVD0}) that is specified as LVD.

3.2 Used Pins

Table 3-1 shows list of used pins and assigned functions.

Table 3-1 List of Pins and Functions

Pin name	Input/Output	Function
P13/EO13	Output	ELCL output signal (LED1 control ^{Note})
P14/EO14	Output	ELCL output signal (LED2 control ^{Note})

Note. Please configure outside the RTK7RLG230CLG000BJ.

Caution. In this application note, only the used pins are processed. When actually designing your circuit, make sure the design includes sufficient pin processing and meets electrical characteristic requirements.

4. Software

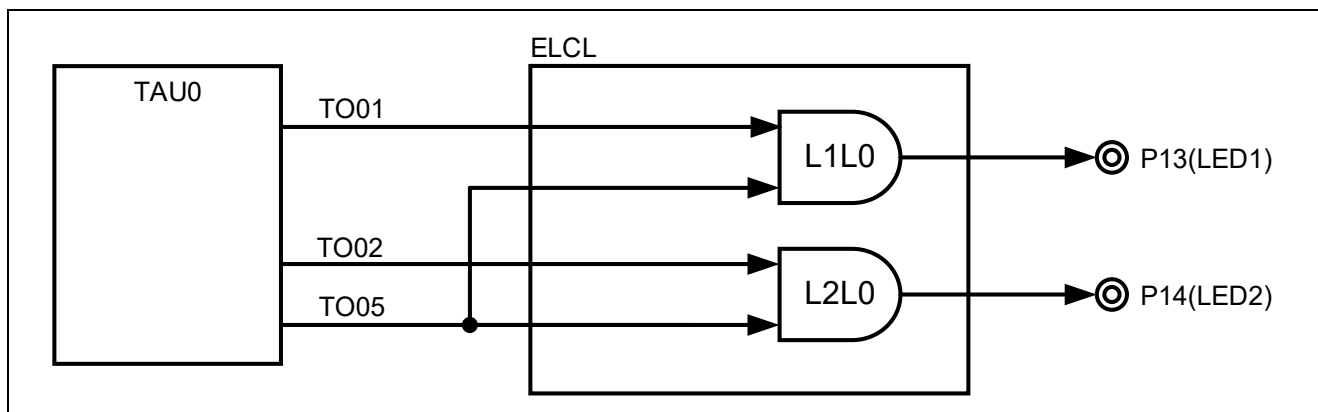
4.1 Overview of the sample program

In this sample code, burst dimming control for two LEDs using PWM output from TAU0 and two ELCL module "AND"s. The signals generated by the burst dimming control circuit are output to P13 and P14.

Figure 4-1 shows the system configuration of the sample code.

Three PWM output signals (TO01, TO02 and TO05) from TAU0 are input to ELCL modules. In the ELCL module, link the three PWM output to the two ANDs (L1L0 and L2L0), and the result of the ANDs of the PWM output of TO05 and PWM outputs of TO01 and TO02 is output. It is possible to check the burst dimming control signal by selecting P13 and P14 as the link destination of the ELCL output signal. TO01 and TO02 are set to different duty cycle, and two LEDs with different dimming rates are illuminated.

Figure 4-1 System configuration of the sample code



4.2 Folder Configuration

Table 4-1 shows folder configuration of source file and header files using by sample code except the files generated by integrated development environment and the files in the bsp environment.

Table 4-1 Folder configuration

Folder/File configuration	Outline	Created by Smart configurator
¥r01an6566_elcl_dimming <DIR> ^{Note2}	Root folder of this sample code	
¥src<DIR>	Folder for program source	
main.c	Sample code source file	
main.h	Sample code header file	
¥smc_gen<DIR>	Folder created by Smart Configurator	√
¥Config_TAU0_0<DIR>	Folder for TAU00 program	√
Config_TAU0_0.c	Source file for TAU00	√
Config_TAU0_0.h	Header file for TAU00	√
Config_TAU0_0_user.c	Interrupt source file for TAU00	√ ^{Note 1}
¥Config_TAU0_4<DIR>	Folder for TAU04 program	√
Config_TAU0_4.c	Source file for TAU04	√
Config_TAU0_4.h	Header file for TAU04	√
Config_TAU0_4_user.c	Interrupt source file for TAU04	√ ^{Note 1}
¥Config_PORT<DIR>	Folder for PORT program	√
Config_PORT.c	Source file for PORT	√
Config_PORT.h	Header file for PORT	√
Config_PORT_user.c	Interrupt source file for PORT	√ ^{Note 1}
¥Config_ELCL<DIR>	Folder for ELCL program	√
Config_ELCL.c	Source file for ELCL	√
Config_ELCL.h	Header file for ELCL	√
Config_ELCL_user.c	Interrupt source file for ELCL	√ ^{Note 1}
¥general<DIR>	Folder for initialize or common program	√
¥r_bsp<DIR>	Folder for BSP program	√
¥r_config<DIR>	Folder for program	√

Note. <DIR> means directory.

Note 1. Not used in this sample code.

Note 2. The IAR version of the sample code contains buildinfo.ipcf. For the ipcf file, refer to "RL78 Smart Configurator User Guide: IAR (R20AN0581)"

4.3 Option Byte Settings

Table 4-2 shows the option byte settings.

Table 4-2 Option Byte Settings

Address	Setting Value	Contents
000C0H/040C0H	1110 1111B (EFH)	Operation of Watchdog timer is stopped (counting is stopped after reset)
000C1H/040C1H	1111 1110B (FEH)	LVD0 operating mode: reset mode Detection voltage: Rising edge 1.90V Falling edge 1.86V
000C2H/040C2H	1110 1000B (E8H)	Flash operating mode: HS mode High-speed on-chip oscillator clock: 32MHz
000C3H/040C3H	1000 0101B (85H)	On-chip debugging is enabled

4.4 Constants

Constants are not used in this sample code.

4.5 Variables

Global variables are not used in this sample code.

4.6 Functions

Table 4-3 shows the functions used in the sample code. However, the unchanged functions generated by the Smart Configurator are excluded.

Table 4-3 Functions

Function name	Outline	Source file
main	Main process	main.c

4.7 Function Specifications

This part describes function specifications of the sample code.

[Function name] main

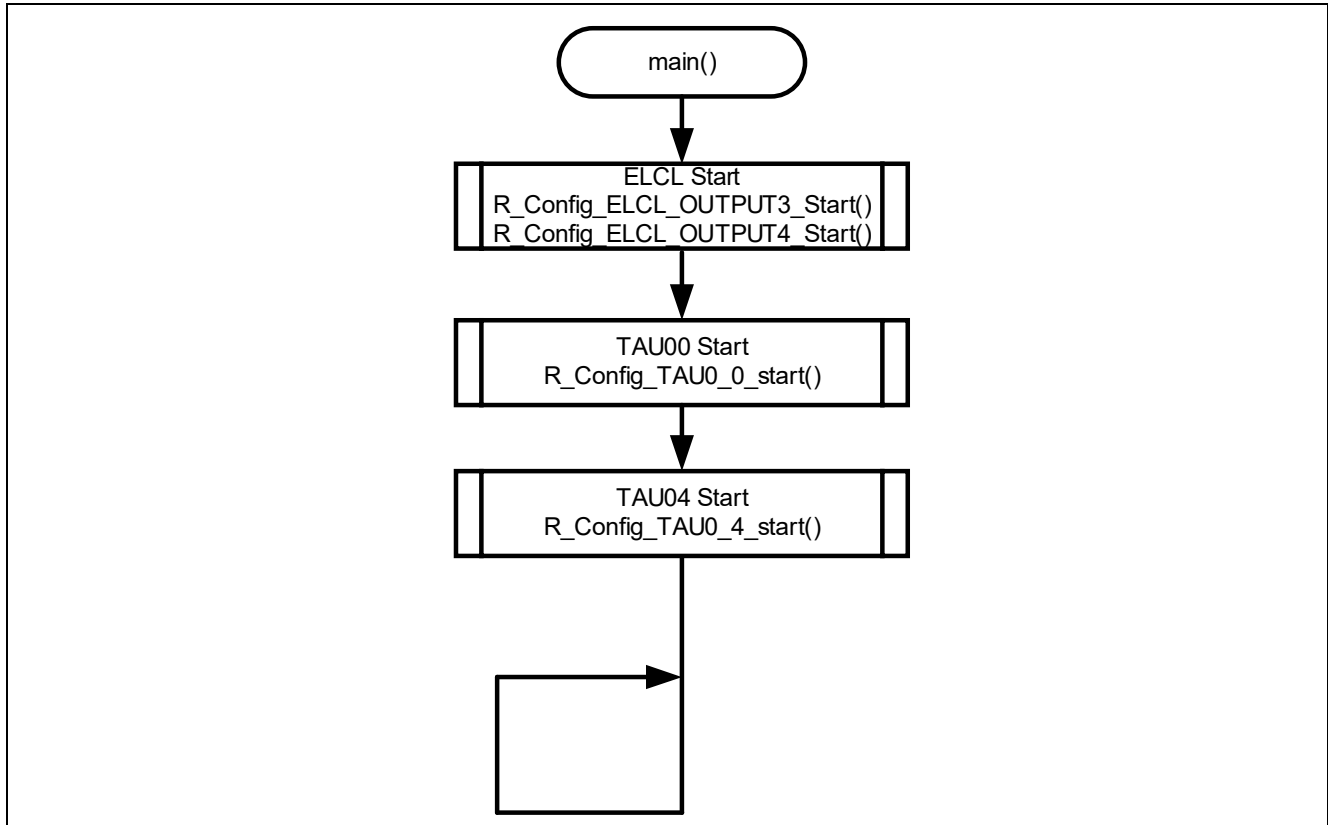
Outline	Main process
Header	r_smc_entry.h
Declaration	void main (void);
Description	This function starts ELCL output and starts the operation of TAU0 channel 0, 1, 2, 4 and 5.
Arguments	None
Return value	None
Remarks	None

4.8 Flow Charts

4.8.1 Main Process

Figure 4-2 shows flowchart of main process

Figure 4-2 Main process



5. Application example

In addition to the sample code, this application note contains the following Smart Configurator configuration files

r01an6566_elcl_dimming.scfg

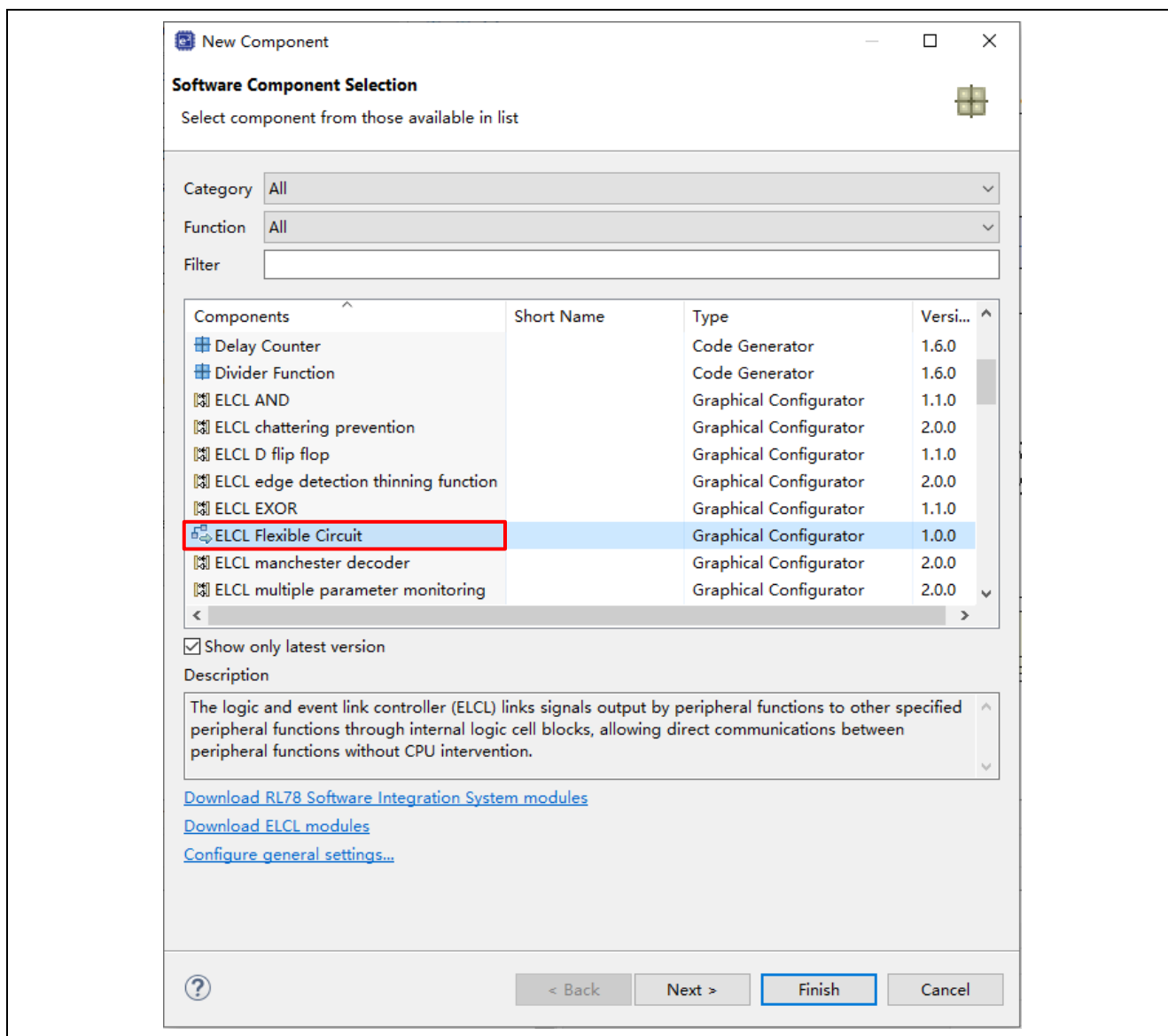
The following is a description of the file and examples of settings and notes for use.

5.1 Setting up the ELCL components

To use the ELCL component, the procedure is shown below.

1. Start the Smart Configurator.
2. Click on the "Components" tag, and then click "Add component".
3. When the "New Component" window shown in Figure 5-1 opens, select "ELCL Flexible Circuit" component and Click "Finish".

Figure 5-1 Add "ELCL Flexible Circuit" component



5.2 r01an6566_elcl_dimming.scfg

This is the Smart Configurator configuration file used in the sample code. It contains all the features configured in the Smart Configurator. The sample code settings are as follows.

Table 5-1 Parameters of Smart Configurator

Tag name	Component	Contents
Clocks	-	Operation mod: High-speed main mode 2.4 (V) ~ 5.5 (V) EV _{DD} setting: $1.8V \leq EV_{DD0} < 5.5V$ High-speed on-chip oscillator: 32MHz f _{IHP} : 32MHz f _{CLK} : 32000kHz (High-speed on-chip oscillator) f _{SXP} : 32.768kHz (Low-speed on-chip oscillator)
System	-	On-chip debug operation setting: COM port ^{Note} Pseudo-RRM/DMM function setting: Used Start/Stop function setting: Unused Trace function setting: Used Security ID setting: Use security ID Security ID: 0x00000000000000000000 Security ID authentication failure setting: Do not erase flash memory data
Components	r_bsp	Start up select : Enable (use BSP startup) Control of invalid memory access detection : Disable RAM guard space (GRAM0-1) : Disabled Guard of control registers of port function (GPORT) : Disabled Guard of registers of interrupt function (GINT) : Disabled Guard of control registers of clock control function, voltage detector, and RAM parity error detection function (GCSC) : Disabled Data flash access control (DFLEN) : Disables Initialization of peripheral functions by Code Generator/Smart Configurator : Enable API functions disable : Enable Parameter check enable : Enable Setting for starting the high-speed on-chip oscillator at the times of release from STOP mode and of transitions to SNOOZE mode : High-speed Enable user warm start callback (PRE) : Unused Enable user warm start callback (POST) : Unused Watchdog Timer refresh enable : Unused
	Config_LVD0	Operation mode setting: Reset mode Voltage detection setting: Reset generation level (V _{LVD0}): 1.86 (V)

Note. When using IAR, use the following settings.

On-chip debug operation setting: Use emulator

Emulator setting: E2 Emulator Lite

Table 5-2 Parameters of Smart Configurator

Tag name	Component	Contents
Components	Config_TAU0_0	<p>Components: PWM Output Resource: TAU0_0 Operation clock: CK00 Clock source: $f_{CLK}/2^6$ Cycle value: 50μs Interrupt setting: unused</p> <p>(slave1) Duty value: 20% Initial output value: 1 Output level: Active-high Output setting: The timer output is only to be used for input to the ELCL and not for the TO01 pin Interrupt setting: unused</p> <p>(slave2) Duty value: 70% Initial output value: 0 Output level: Active-high Output setting: The timer output is only to be used for input to the ELCL and not for the TO02 pin Interrupt setting: unused</p>
	Config_TAU0_4	<p>Components: PWM Outout Resource: TAU0_4 Operation clock: CK01 Cycle value: f_{CLK} Cycle value: 2μs Interrupt setting: unused</p> <p>(slave5) Duty value: 50% Initial output value: 0 Output level: Active-high Output setting: The timer output is only to be used for input to the ELCL and not for the TO05 pin Interrupt setting: unused</p>
	Config_PORT	<p>Components: Ports Port selection: PORT1 P13: Out (Output ELCL output signal) P14: Out (Output ELCL output signal)</p>

Table 5-3 Parameters of Smart Configurator

Tag name	Component	Contents
	Config_ELCL	<p>Components: ELCL Flexible Circuit</p> <p>(Detail setting: Input) Output from TAU0 channel 1 Output from TAU0 channel 2 Output from TAU0 channel 5</p> <p>(Detail setting: L1L0, AND) Input 0: Output from TAU0 channel 1 Input 1: Output from TAU0 channel 5 Output: SAU0 ch1 fSCK/TAU0 ch0 input/P13</p> <p>(Detail setting: L2L0, AND) Input 0: Output from TAU0 channel 2 Input 1: Output from TAU0 channel 5 Output: SAU0 ch0 receive/TAU0 ch1 input/P14</p> <p>(Detail setting: Output) Output of signal 3: SAU0 ch1 fSCK/TAU0 ch0 input/P13 Output of signal 4: SAU0 ch0 receive/TAU0 ch1 input/P14</p>

5.2.1 Clocks

Set the clock used in the sample code.

5.2.2 System

Set the on-chip debug of the sample code.

"Control of on-chip debug operation" and "Security ID authentication failure setting" affect "On-chip debugging is enabled" in "Table 4-2 Option Byte Settings". Note that changing the settings.

5.2.3 r_bsp

Set the startup of the sample code.

5.2.4 Config_LVD0

Set the power management of the sample code.

Affects "Setting of LVD0" in "Table 4-2 Option Byte Settings". Note that changing the settings.

5.2.5 Config_TAU0_0

Set the TAU00 in the sample code.

In the sample code, two PWM outputs with different duty cycle are used for dimming control. The LED brightness can be controlled by changing the duty cycle for each channel.

Interrupt is not used.

5.2.6 Config_TAU0_4

Set the TAU04 in the sample code.

In the sample code, PWM output with a duty cycle of 50% is used as a LED drive signal.

Interrupt is not used.

5.2.7 Config_PORT

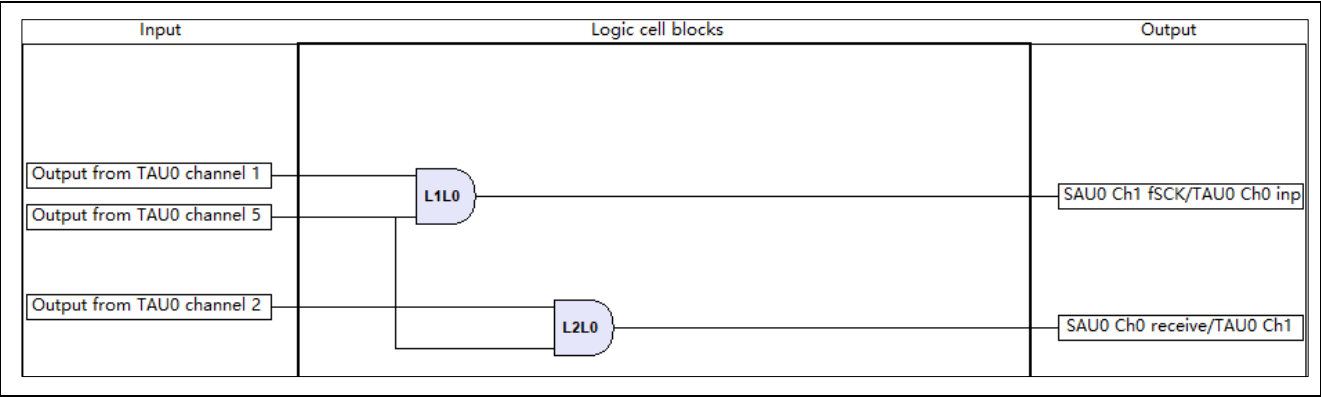
Set the port in the sample code.

In the sample code, P13 and P14 set as ELCL output signal and connected to LED1 and LED2.

5.2.8 Config_ELCL

Set up ELCL circuit as Figure 5-2 ELCL_Config setting in the sample code.

Figure 5-2 ELCL_Config setting



6. Sample Code

Sample code can be downloaded from the Renesas Electronics website.

7. Reference

RL78/G23 User's Manual: Hardware (R01UH0896E)

RL78 Family User's Manual: Software (R01US0015E)

RL78 Smart Configurator User's Guide: CS+ (R20AN0580E)

RL78 Smart Configurator User's Guide: e² studio (R20AN0579E)

RL78 Smart Configurator User's Guide: IAREW (R20AN0581E)

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Revision History

Rev.	Date	Description	
		Page	Summary
1.00	Sep.26.22	-	First edition
2.00	Jul.22.25	-	Update to use Smart Configurator "ELCL Flexible Circuit" component to make application design instead of using "ELCL AND" component. - Deleted Config_AND configuration created by "ELCL AND" component - Added Config_ELCL configuration created by "ELCL Flexible Circuit" component - Added Config_PORT configuration and setting item using for ELCL output
		5	Updated Table 2-1 Operation Confirmation Conditions

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1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity.

Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).

7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

8. Differences between products

Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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